

# **MICROELECTRONICS PACKAGING HANDBOOK**

## ***Subsystem Packaging***



**PART III**



**Second Edition**

Edited by

**Rao R. Tummala**

**Eugene J. Rymaszewski**

**Alan G. Klopfenstein**

# Microelectronics Packaging Handbook

**R. R. Tummala, Eugene J  
Rymaszewski, Alan G Klopfenstein**



## **Microelectronics Packaging Handbook:**

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